Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.

**ANODE**

**.024 x .024”**

**.040”**

**.040”**

**Top Material: Al**

**Backside Material: Ti/Ni/Ag**

**Bond Pad Size: .024 x .024”**

**Backside Potential: CATHODE**

**Mask Ref: SENS557**

**APPROVED BY: DK DIE SIZE .040” X .040” DATE: 11/10/21**

**MFG: SENSITRON THICKNESS .009” P/N: 1N5806**

**DG 10.1.2**

#### Rev B, 7/1